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Siemens Digital Industries Software

2019 Electronics and Semiconductor Executive Council meeting

Shanghai, China • September 17-18, 2019

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Dear trusted partners and customers,

I am pleased to invite you to our 2019 Electronics and Semiconductor Executive Council Meeting, which will be held on September 17 and 18, 2019 at the Hyatt on the Bund (Huangpu River) in Shanghai, China.

The primary goal of the council is to assemble a select group of trusted thought leaders across the electronics and semiconductor communities to help mold the future of our solutions as we continue to address the needs of this rapidly changing and growing market. We are honored to continue building a strategic partnership that enables you to influence the direction of our industry roadmap. This will be a chance to learn, network and hear from your peers in the industry through interactive, informative and engaging discussions. The goal is to provide significant value for all in attendance, and your presence will ensure success for all participants.

We look forward to meeting you in Shanghai.

Please take a moment to RSVP, to confirm your attendance, as seating is limited, and invitations are personal and exclusive.

Yours sincerely,

Fram Akiki

Vice President
Electronics and Semiconductor Industry
Siemens Digital Industries Software, Inc.

Fram Akiki

Prior to joining Siemens, Fram was an executive for 12 years with Qualcomm in their chipset division and spent 21 years with IBM in their microelectronics group. Fram has over 30 years of experience in the electronics and semiconductor industry. Fram holds a B.S. in Electrical and Computer Engineering from Clarkson University, and an M.S. in Electrical Engineering and a M.B.A. in International Business from The University of Vermont. He has authored a number of white papers, holds a patent on RFID/cellular connectivity for the IoT market and is an adjunct instructor at Clarkson University.

Why participate?

- We've gathered together trusted executive thought leaders across the electronics and semiconductor communities
- You will be able to network with your peers from companies like Lenovo, TSMC, Tokyo Electron, Renesas Electronics, Mettler Toledo, Applied Materials, AMD, Dell, Jabil, Samsung and many others
- Every participant is invited to present to the group on 1-2 key solution topics that are important to them and their business. We will provide some suggested topics for your consideration
- There will be separate electronics and semiconductor focused workshops to discuss the key topics raised with fellow executives and Siemens executives
- The feedback and information gathered during the meeting will provide key input into the Siemens Digital Industries Software roadmap process
- There will be an official report that will include all critical feedback from the meeting and will be shared exclusively with the participants of the meeting

Interactive workshops

Electronics:

- Digitalization – The impact, challenges, and the opportunities
- Smart manufacturing for electronics
- Electronic systems design (ESD)
- Performance engineering, simulation and test
- Electronics lifecycle management

Semiconductor:

- Digitalization – The impact, challenges, and the opportunities
- Smart manufacturing for semiconductors
- Requirements management and verification
- Semiconductor package design
- Thermal reliability
- Semiconductor lifecycle management

Electronics keynote

Mr. Johnson Jia –
SVP, Lenovo Group

Johnson Jia graduated from the Beijing Institute of Technology with a Master's Degree in Automated Control. He also holds an Executive MBA Degree from one of China's top rated academic institutions, Tsinghua University. Johnson joined Lenovo China in 1995, and possesses more than 20 years' experience competing in what has become the world's fastest growing PC market. He has cross functional experience in Desktop R&D, Consumer Electronics Business, North America Sales and Consumer Desktop PC Business, Global procurement and Global Operations.

Semiconductor keynote

Mr. Roger Luo –
President of TSMC Nanjing

Mr. Roger Luo was born in Taiwan, and his ancestors came from Jiangxi, China. Mr. Luo received his MBA degree from China Peking University, and EE B.S. degree from Taiwan Chiao-Tung University. Mr. Luo has been serving in Semiconductor industry for over 30 years. Before TSMC, he held engineering management positions at ERSO/ITRI (Electronics Research Lab, Industrial Technology Research Institute) and Twinhead International Corp. Mr. Luo joined TSMC in 1994. He was previously Executive of Asia Account Management and Chief Operation Officer, TSMC-Europe. Since Mr. Luo was appointed Leader of China Business Development in 2003 and TSMC Nanjing in 2016, he has dedicated himself to the development and growth of Chinese semiconductor business.

Special guest

Dr. Walden Rhines

Walden C. Rhines is CEO Emeritus of Mentor, a Siemens business, focusing on external communications and customer relations. He was previously CEO of Mentor Graphics for 25 years and Chairman for 17 years. During his tenure at Mentor, revenue nearly quadrupled and market value increased 10X. Prior to Mentor Graphics, Dr. Rhines was Executive Vice President, Semiconductor Group, responsible for TI's worldwide semiconductor business. Dr. Rhines holds a Bachelor of Science degree in engineering from the University of Michigan, a Master of Science and PhD in materials science and engineering from Stanford University, and a Master of Business Administration from Southern Methodist University.

Agenda

Time	Agenda – Tuesday, September 17	Presenter
8:00 a.m.	Arrival – Registration	
8:30 a.m.	Welcome and introduction	Fram Akiki, Siemens Digital Industries Software
8:45-9:30 a.m.	Electronics Keynote	Johnson Jia, SVP, Lenovo
9:30-10:15 a.m.	Semiconductor Keynote	Roger Luo, President of TSMC Nanjing
10:15-10:30 a.m.	Siemens Keynote	Fram Akiki, Siemens Digital Industries Software
10:30-10:45 a.m.	Morning break	
10:45-12:00 p.m.	Digital Thread presentations	Customers
12:00-1:00 p.m.	Lunch break	
1:00-3:00 p.m.	Digital Thread presentations continue	Customers
3:00-3:15 p.m.	Afternoon break	
3:15-5:00 p.m.	Digital Thread presentations continue	Customers
5:00-5:15 p.m.	Wrap-up for the day	
6:30-9:30 p.m.	Dinner	

Time	Agenda – Wednesday, September 18	Presenter
8:00 a.m.	Arrival	
8:30-11:30 a.m.	Digital Thread Workshop – Electronics	Vincent Chen, Siemens Digital Industries Software
8:30-11:30 a.m.	Digital Thread Workshop – Semiconductor	Jupiter Wang, Siemens Digital Industries Software
11:30-12:30 p.m.	Group discussion and Wrap-up	Fram Akiki, Siemens Digital Industries Software
12:30-2:00 p.m.	Lunch break and networking	

>> To register go to: www.siemens.com/esec

The 2019 Electronics and Semiconductor Executive Council Meeting Official Report will be shared exclusively with the participants of the meeting and will include critical feedback from the meeting

The report will include:

- Key points and information from the keynote presentations
- Customer and guest presentations, perspectives and Q&A interactions
- An overview of the Electronics and Semiconductor Workshop discussions, findings and key takeaways
- An industry analyst 3rd party perspective
- The report may also include industry statistics, references or metrics to support key findings and conclusions

The report is exclusive and will only be provided to participants of the meeting, and will be sent directly to the recipients as soon as it is available.

Networking and entertainment – Huangpu River Cruise followed by dinner

- We'll take a 60 minute cocktail cruise departing from the Bund (Zhongshan Road), sailing to the Huangpu Bridge in the south, then head north towards Wusongkou, and then return to the Bund for dinner
- The Huangpu River, is 114 kilometers (71miles) long and 400 meters (0.25 miles) wide. The river divides Shanghai into east and west
- The west bank (Puxi) of the Huangpu River is the cultural, residential and entertainment center of Shanghai
- The east bank of the river (Pudong) is the newer district of Shanghai and its financial and commercial hub

Hotel booking link:

Venue:
The Hyatt on the Bund
(Huangpu River)
199 Huang Pu Road
Shanghai, China
200080

For more information, contact:

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>> To register go to: www.siemens.com/esec